ASSOCIATION CONNEC	Material Comp © Copyright 2005. I international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
Supplier Info	rmation															
Company name*				Company unique ID			Unique ID Authority					Response Date*				
nsemi											2022-02-11					
Contact Name		Title - Contact			]	Phone - Contact*				Email - Contact*						
Product-Env-Ste	ewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Repr	esentative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Reque	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Dat	e Vers	sion	Manufacturing Site		V	Weight*	UOM	Unit Type	
		NCP81381MNTXG Integrated Dri		Integrated Driver	and MOSFET 20		2022-02-11	)2-11		PH1		1	.01.13	mg	Each	
Ianufacturin	ng Proccess Informa	tion												·		
Terminal Plating / Grid Array Material			Cerminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperature Max		ure Max T	ime at Peak	Temperati	ure Numb	per of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 3			260	<b>260</b> C		30 seco		secono	ds 3				
omments																
TTENTION: M	ISL 3 Rated item require	es Bake and D	Ory Pack (afte	r electrical test)												
or more inform	ation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content is the content of	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.02	mg	Supplier	Silicon (Si)	7440-21-3		3.02	mg
Die Attach Solder	5.35	mg	Supplier	Silver (Ag)	7440-22-4		0.1338	mg
			A	Lead (Pb)	7439-92-1	7a	4.9488	mg
			Supplier	Tin (Sn)	7440-31-5		0.2675	mg
Lead Frame	59.54	mg	Supplier	Silver (Ag)	7440-22-4		0.9824	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0714	mg
			Supplier	Iron (Fe)	7439-89-6		1.3992	mg
			Supplier	Copper (Cu)	7440-50-8		57.0691	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0179	mg
Mold Compound-Black	31.34	mg	Supplier	Epoxy resins	129915-35-1		1.567	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.567	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1254	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7208	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.639	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.7208	mg
Plating	1.57	mg	Supplier	Tin (Sn)	7440-31-5		1.57	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg